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LEADFRAME PEDESTALS FOR UNIFORM DIE ATTACH

ABSTRACT OF THE DISCLOSURE

A leadframe assembly including a semiconductor die coupled to a mounting area includes at least three pedestals extending above the surface of the mounting area. The pedestals are of the same height and contact the bottom surface of the semiconductor die which is joined to the mounting area by an adhesive formed continuously over the mounting area. The method for forming the leadframe includes forming the pedestals by stamping a malleable leadframe or joining separately formed pedestals to the mounting area. The method further provides for forming an adhesive on the mounting area and joining the semiconductor die to the leadframe such that the adhesive advantageously extends along the sides of the semiconductor die.

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